Upgrade of the silicon part

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Why silicon upgrade



- We have to define the main reason for silicon upgrade
- Proton-Light Ion Run?
- Other 'parasitic' run that could happen in next few years?
 P-Xe in 2017
- This presentation will not focus on a possibile far future new experiment, but on a 'simple' upgrade of the silicon part of the existing LHCf detector

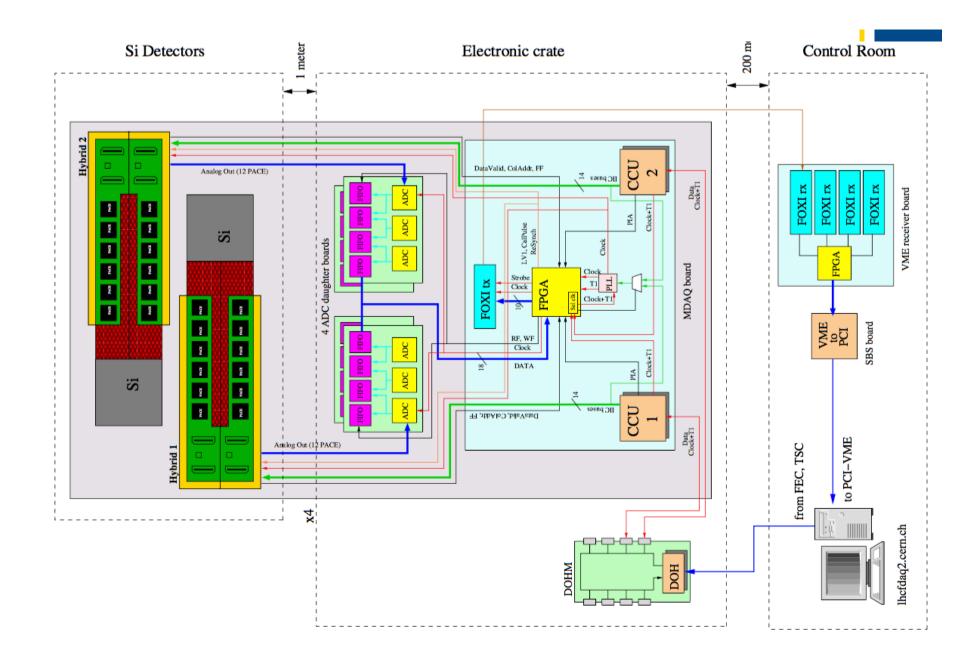
The main parts of LHCf silicon subdetector

Silicon detectors

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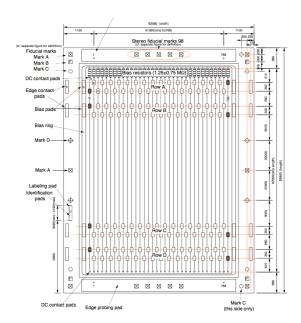
- Front end hybrids
 - Pace3 chips
- Power distribution board
- MDAQ boards
- Control ring to control PACE3
- Optical link for data and VME receiver

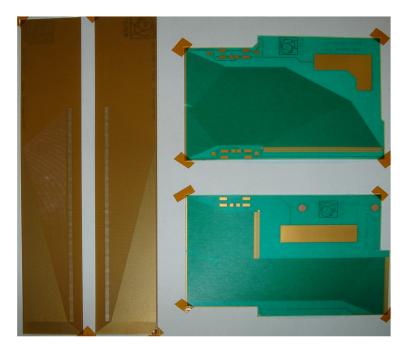




Silicon detectors and kapton fanouts

- This part has already been modified before the 13 TeV p-p run to increase dynamic range, new sensors with a particular bonding pattern → Ok
- I think is not possible and not necessary to upgrade it
 - Not necessary because no physics limitations due to sensors
 - Not possible because of money

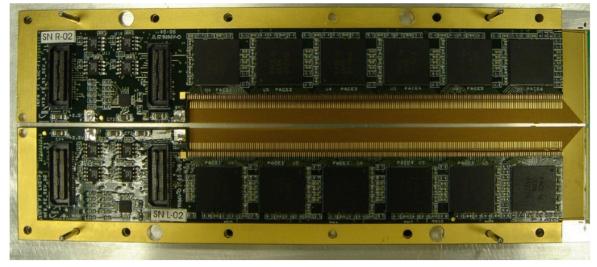






+ Front end hybrids and Pace3 chips

- The hybrids have been completely rebuilt few years ago for:
 - Solve few minor problems existing in the old version
 - Reset signal was missing
 - Few chips were broken
 - Assembly of new kapton fanout in the Hybrid zone
- I think it is not possible to upgrade this part because no more PACE3 chips are available from CMS
 - It is completely not realistic to think to use different chips
 - The dynamic range is adequate



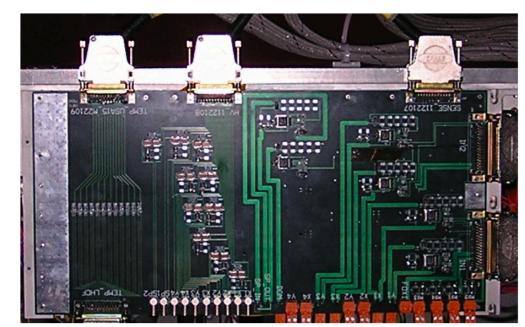


Power distribution board

- The Power Distribution Board is used to handle the voltage generator for all the silicon part
 - Linear regulators

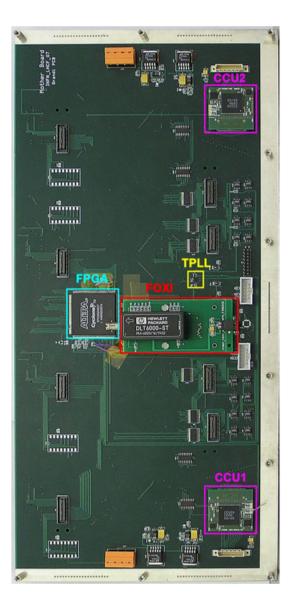
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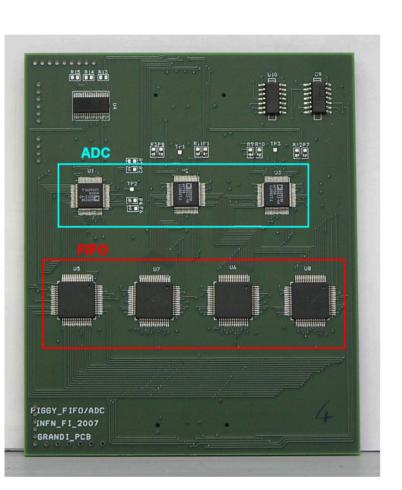
- Sense wires connection for Agilent Power Supply
- A problem on connectors appeared during the first p-Pb run
- Connectors have been changed
- No major issues















- The MDAQ Boards are used to:
 - Generate the control signals for the Pace3 chips by using custom chips developed by CERN
 - CCU
 - Clock re-generator
 - ADC conversion
 - DAQ sequence handling with Finite State Machine on Altera FPGA
 - Temporary data storage on FIFO
 - Interface the data with the optical link transmission
 - Interface with the ring to control the Pace3

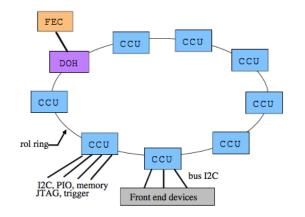


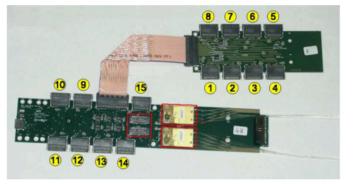


- Some critical issues related to MDAQ are present:
 - Boards are very large, and difficult to handle
 - Very large electronic box is necessary
 - Interface with the FOXI transmitter is very weak for the mechanical point of view
- Can we do new MDAQ boards?
- In principle it is possible, even if:
 - No anymore custom chips to regenerate the clock are available from Cern
 - No anymore ADC chips are available form CERN
- We can study how to implement new MDAQ boards with commercial chips

+ Control ring for Pace3

- A dedicated control ring is necessary to:
 - Send commands to Pace3 chips
 - Distribute clock, reset and trigger
 - Handle the redundancy (never used up to now!)
- The system is working well and can be used it again
- The only real problem is the PC used to control the ring
 - FEC and TSC boards
 - Driver not working on recent Linux distribution
 - A very old and not safe PC should be used







Optical link for data and VME Receiver



Most critical issue

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- The Taxi chips are very obsolete
- Some optical fibers in the tunnel are damaged and spares have been used
- The VME receiver board is always creating problems
 - Works only in some slots
 - CRC errors are often present in variable fraction
- The Data Transmission system should be completely redesigned
- This is the most important and necessary item for Silicon Upgrade

Optical link for data and VME Receiver

- For the moment we do not have a real proposal
- Should we use optical or copper link?
 - Fast Gbit ethernet protocol?

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- How we install new cables or new fibers in the tunnel?
- Which receiver board should we use?
- The system on the Front End side should be interfaced with the MDAQ boards
 - New or old MDAQ boards?

